

Amendments to the Claims:

Please cancel claims 51, 52 and 57, and please amend claims 48, 53, 55, 58 and 59 as follows:

1-47. (Cancelled)

¹
~~48.~~ (Currently amended) A system for restoring a contact surface of a processing pad used in processing microelectronic workpieces, comprising:

a table for supporting the processing pad;

an end-effector carrier assembly having a holder positionable over the table; and
an end-effector carried by the holder, the end-effector comprising a conditioning

surface configured to engage the contact surface of the processing pad, and a plurality of microstructures on the conditioning surface, the microstructures being arranged in a pattern corresponding to a desired pattern of microfeatures on the contact surface of the processing pad, and the microstructures being raised elements projecting from the conditioning surface and/or depressions in the conditioning surface.

²
~~49.~~ (Original) The system of claim ¹~~48~~ wherein:

the end-effector comprises a plate having a backside with a joint for connecting the plate to a holder and the conditioning surface defines a front side of the plate; and

the microstructures comprise raised features spaced apart from one another in the pattern.

³
~~50.~~ (Original) The system of claim ¹~~48~~, further comprising a heater carried by the end-effector.

⁴
51. (Cancelled)

52. (Cancelled)

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53. (Currently amended) A system for restoring a contact surface of a processing pad used in processing microelectronic workpieces, comprising:

a table for supporting the processing pad;

an end-effector carrier assembly having a holder positionable over the table; and

an end-effector carried by the holder, the end-effector comprising a plate having

a conditioning surface configured to engage the contact surface of the processing pad and a plurality of microstructures on the conditioning surface, the microstructures being spatially arranged in a pattern corresponding to a desired pattern of microfeatures to be imparted on the contact surface of the processing pad, and the microstructures being raised elements projecting from the conditioning surface and/or depressions in the conditioning surface.

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54. (Original) The system of claim 53, further comprising a heater carried by the end-effector.

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55. (Currently amended) A system for restoring a contact surface of a processing pad used in processing microelectronic workpieces, comprising:

a table for supporting the processing pad;

an end-effector carrier assembly having a holder positionable over the table; and

an end-effector carried by the holder, the end-effector comprising a cylindrical

conditioning surface configured to engage the contact surface of the processing pad and the end-effector being rotatable about an axis, and the end-effector further including a plurality of microstructures on the conditioning surface, the microstructures being spatially arranged in a pattern corresponding to a desired pattern of microfeatures to be imparted on the contact surface of the processing pad, and the microstructures

being raised elements projecting from the conditioning surface and/or depressions in the conditioning surface.

⁷
~~56~~. (Original) The system of claim ⁶~~55~~, further comprising a heater carried by the end-effector.

⁵
57. (Cancelled)

⁸
~~58~~. (Currently amended) ~~The system of claim 57, further comprising A~~
system for restoring a contact surface of a processing pad used in processing
microelectronic workpieces, comprising:

a table for supporting the processing pad;

an end-effector carrier assembly having a holder positionable over the table;

an end-effector carried by the holder, the end-effector comprising a conical
conditioning surface configured to engage the contact surface of the
processing pad and the end-effector being rotatable about an axis, and
the end-effector further having a plurality of microstructures on the
conditioning surface, the microstructures being spatially arranged in a
pattern corresponding to a desired pattern of microfeatures to be imparted
on the contact surface of the processing pad, and the microstructures
being raised elements projecting from the conditioning surface and/or
depressions in the conditioning surface; and

a heater carried by the end-effector.

⁹
~~59~~. (Currently amended) A system for restoring a contact surface of a
processing pad used in processing microelectronic workpieces, comprising:

a table for supporting the processing pad;

an end-effector carrier assembly having a holder positionable over the table;

an end-effector carried by the holder, the end-effector comprising a conditioning surface configured to engage the contact surface of the processing pad;
and
a heat source coupled to the end-effector to provide heat to the conditioning surface.

10
~~60~~ (Original) The system of claim *9* ~~59~~, further comprising microstructures on the conditioning surface.

11
~~61~~ (Original) The system of claim *10* ~~60~~ wherein the microstructures comprise raised features projecting from the conditioning surface.

12
~~62~~ (Original) The system of claim *10* ~~60~~ wherein the microstructures comprise depressions in the conditioning surface.

13
~~63~~ (Original) The system of claim *9* ~~59~~ wherein the end-effector comprises a plate.

14
~~64~~ (Original) The system of claim *9* ~~59~~ wherein the end-effector comprises a cylindrical roller.

15
~~65~~ (Original) The system of claim *9* ~~59~~ wherein the end-effector comprises a conical roller.

16
~~66~~ (Original) The system of claim *9* ~~59~~ wherein the holder comprises an arm and the carrier further comprises a rotary drive unit connected to the arm to rotate the arm, and wherein the end-effector is attached to the arm.

67-101. (Cancelled)

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